Contact Name Title - Contact Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product Enviro Compliance Title - Representative Phone - Contact* Phone - Contact* Product-Env-Stewards@onsemi.com Phone - Representative* Email - Representative* Email - Representative* Product-Env-Stewards Product-Env-Stewards Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM U	IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company name* Company unique ID Unique ID Authority Response Date* 2025-06-05 Contact Name Title - Contact Phone - Contact* Phone - Contact* Phone - Contact* Product-Env-Stewards Product-Env-Stewa	752-21.1											als and Mf	g Informati	on	
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Product Envisor Compliance Title - Representative* Product Enviro Compliance Title - Representative Product Enviro Compliance Phone - Representative* Product Enviro Compliance NA Product Enviro Stewards @onsemi.com NA Product Enviro Compliance NA Product Env-Stewards @onsemi.com NA	nsemi											2025-06-05			
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Product Enviro Compliance Requester Item Number Requester	ontact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM U Annufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy SnAgCu CU Alloy Terminal Site NA Product-Env-Stewards@onsemi.com Manufacturing Site Weight* UOM U MY1 1.25031 mg E Max Time at Peak Temperature Number of Reflow Cycles SnAgCu CU Alloy 1 260 C 30 seconds 3 Comments	Product-Env-Stewar	rds		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represen	ntative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
FAN53611AUC11X DC/DC 6MHz Buck 1A 2025-06-05 MY1 1.25031 mg E Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles	Product-Env-Stewar	rds		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles SnAgCu CU Alloy 1 260 C 30 seconds 3	Requester	Requester Item Number Mfr I		Item Number Mfr Item Name			Effe		Version	N	Ianufacturing Site	W	eight*	UOM	Unit Type
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SnAgCu CU Alloy 1 260 C 30 seconds 3 comments				arminal Paga	Alloy	STD 020 MSI	Dating	Dook Prog	age Dody T	'amparatur	May Time at Peak	Tomporatu	ra Numb	or of Potlaw Cua	lac
omments				•		S I D-020 MSL	2 Kanng							er of Reflow Cyc	ies
			C	O Alloy	1			200		IC	30	second	8 3		
ver 1 - maximum ume at peak temperature uurmg soldering is 10-50 seconds		me at neals townst	a dunina1	domina ia 10-1	10 seconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of					
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.873382	mg	Supplier	Silicon (Si)	7440-21-3		0.8734	mg
Protection coat	0.011543	mg		Polyimide	proprietary data		0.0115	mg
Solder Ball	0.36503	mg	Supplier	Silver (Ag)	7440-22-4		0.0146	mg
			Supplier	Tin (Sn)	7440-31-5		0.3486	mg
			Supplier	Copper (Cu)	7440-50-8		0.0018	mg
Under Bump Metal	3.55E-4	mg	Supplier	Titanium (Ti)	7440-32-6		0	mg
			В	Nickel (Ni)	7440-02-0		0.0002	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0	mg